

Kulicke & Soffa Industries, Inc.

Kulicke & Soffa to Participate at SMT Hybrid Packaging 2016

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), announced today that it will be exhibiting at the SMT Hybrid Packaging trade show, Europe's leading event on system integration in microelectronics. The event will be held in Nuremberg, Germany, from April 26 to 28, 2016.

Kulicke & Soffa will be at the SMT Hybrid Packaging trade show booth 7A-321, showcasing its market leading packaging solutions.

- The Asterion™ - a single platform hybrid wedge bonder with the capability to handle a multitude of interconnect materials including large and small aluminum wire, copper wire, *PowerRibbon™*, as well as aluminum copper-clad ribbon. In addition, the Asterion's interconnect bonding technology has recently been extended to battery applications.
- The iFlex - its new design features an increase in feeder capacity, achieving 25% more feeder positions. Combining this increased feeder capacity, with the high volume and high quality iX system delivers the Flexline, which offers best-in-class flexibility, fast changeovers, lower cost-of-ownership and the lowest defect rates.
- The Hybrid - a multi-application solution for advanced packaging with one of the industry's lowest defect rates and highest throughput. It delivers placement accuracy up to 7µm, making it ideal for wafer level packaging, Fan-Out Wafer Level Packaging (FOWLP), System-in-Package (SiP), Multi-chip module (MCM), flip-chip, modules and embedded components. Having evolved from the high speed AX/iX product family, the Hybrid is highly capable of placing both active and passive components with a single platform.
- The IConnPS ProCu *PLUSTM* - a ball bonder with the new ProCu5 process offering the highest level of Copper Process Capability available, with added controls and improvements. ProCu5 enables robust wire bonding production for advanced node wafers with 28 nanometer or below. In addition, it has the capability to bond silver alloy wire with ProAg feature and aluminum fine wire with wedge-to-wedge feature.

Please contact your local sales and services representative for more information on K&S' comprehensive solutions.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, advanced SMT, wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

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